

## 1. General description

Silicon Carbide Schottky diode in a DFN 8\*8 plastic package, designed for high frequency switched-mode power supplies.



## 2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability  $I_{FSM}$
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

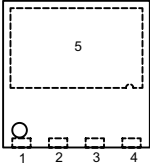
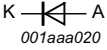
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
<b>Absolute maximum rating</b>							
$V_{RRM}$	repetitive peak reverse voltage			650			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_c \leq 153$ °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		10			A
$T_j$	junction temperature			-55 to 175			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
$V_F$	forward voltage	$I_F = 10$ A; $T_j = 25$ °C; <a href="#">Fig. 5</a>	-	1.29	1.45	V	
		$I_F = 10$ A; $T_j = 150$ °C; <a href="#">Fig. 5</a>	-	1.45	1.65	V	
<b>Dynamic characteristics</b>							
$Q_r$	recovered charge	$I_F = 10$ A; $di_F/dt = 500$ A/ $\mu$ s; $V_R = 400$ V; $T_j = 25$ °C; <a href="#">Fig. 7</a>	-	24	-	nC	

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		
2	n.c.	not connected		
3	A	anode		
4	A	anode		
5	K	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC6D10650T	DFN8*8	WNSC6D10650T6J	Tape	3000	DFN8X8N	25-Dec-2019

## 7. Marking

Table 4. Marking codes

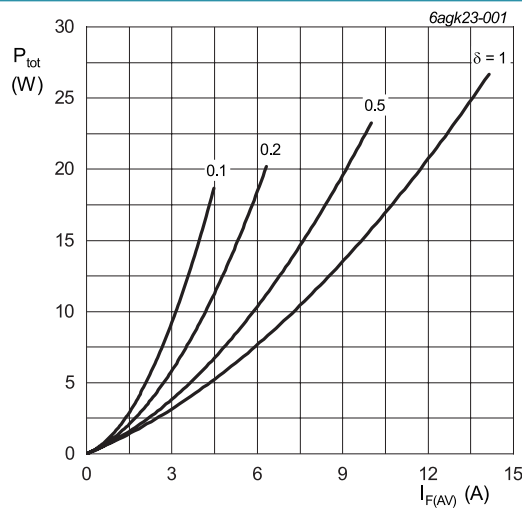
Type number	Marking codes
WNSC6D10650T	WNSC6D 10650T

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

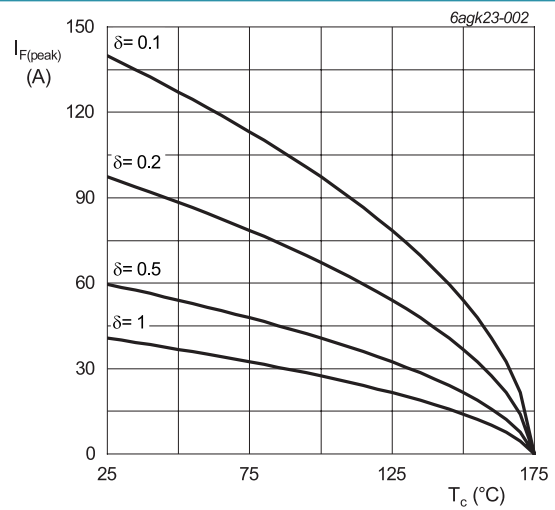
Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{RWM}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_c \leq 153\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		10	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_c \leq 153\text{ }^\circ\text{C}$ ; square-wave pulse		20	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse		75	A
		$t_p = 10\text{ }\mu\text{s}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; square-wave pulse		800	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; $t_p = 10\text{ ms}$		28.125	$\text{A}^2\text{s}$
$T_{\text{stg}}$	storage temperature			-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature			-55 to 175	$^\circ\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 0.829\text{ V}; R_s = 0.0748\text{ }\Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Current derating as a function of case temperature**

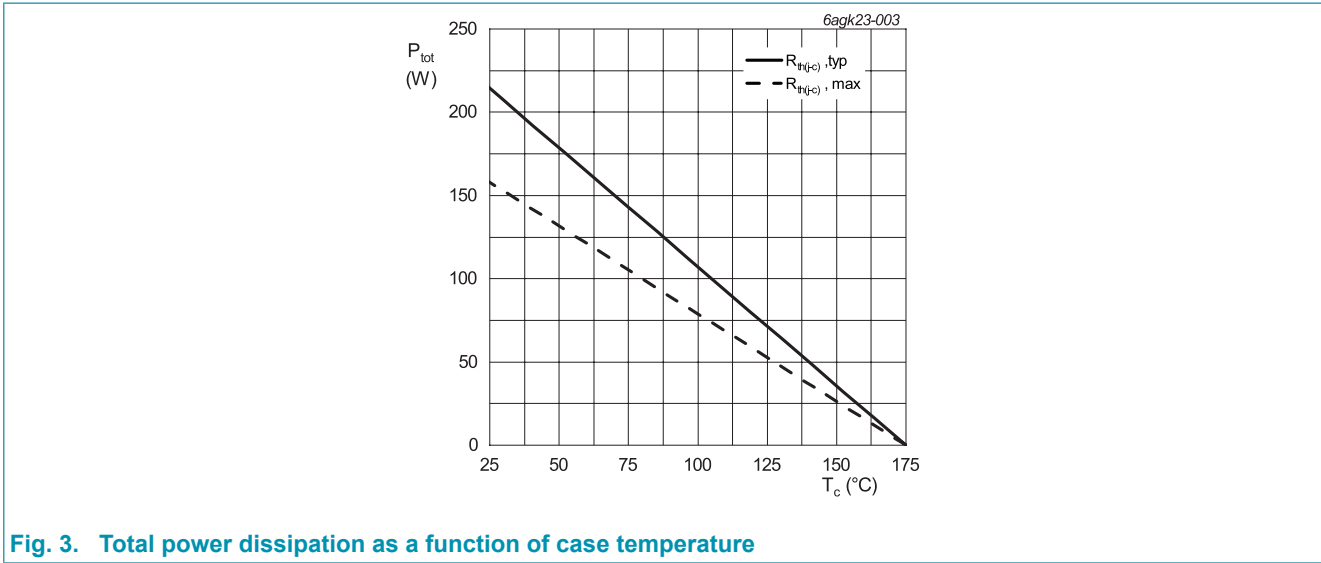


Fig. 3. Total power dissipation as a function of case temperature

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	<a href="#">Fig. 4</a>		-	0.7	0.95	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	60	-	K/W

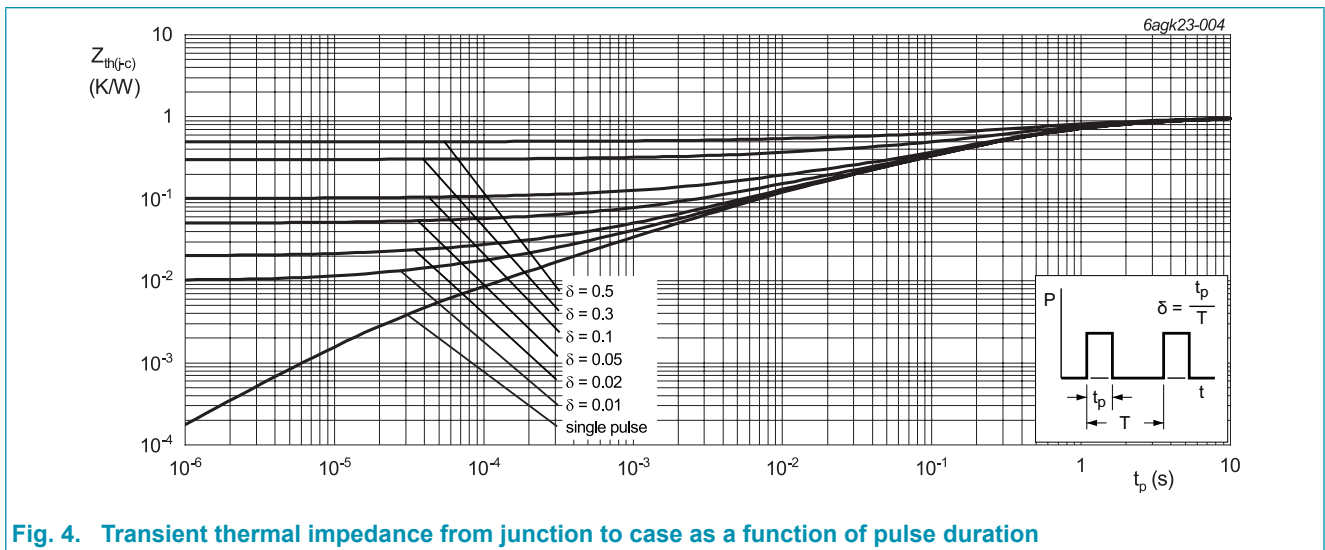
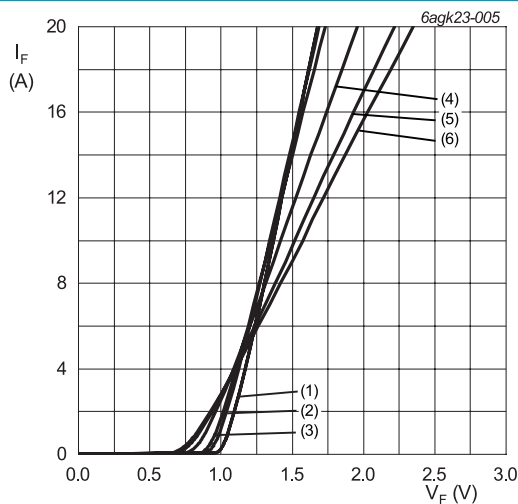


Fig. 4. Transient thermal impedance from junction to case as a function of pulse duration

### 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
<b>Static characteristics</b>							
V <sub>F</sub>	forward current	I <sub>F</sub> = 10 A; T <sub>J</sub> = 25 °C; Fig. 5		-	1.29	1.45	V
		I <sub>F</sub> = 10 A; T <sub>J</sub> = 150 °C; Fig. 5		-	1.45	1.65	V
		I <sub>F</sub> = 10 A; T <sub>J</sub> = 175 °C; Fig. 5		-	1.50	1.70	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>J</sub> = 25 °C; Fig. 6		-	1	50	μA
		V <sub>R</sub> = 650 V; T <sub>J</sub> = 175 °C; Fig. 6		-	15	200	μA
<b>Dynamic characteristics</b>							
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 10 A; V <sub>R</sub> = 400 V; di <sub>F</sub> /dt = 500 A/μs; T <sub>J</sub> = 25 °C; Fig. 7		-	24	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>J</sub> = 25 °C		-	500	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>J</sub> = 25 °C		-	58	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>J</sub> = 25 °C		-	52	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 5 A; L = 5 mH; T <sub>J(init)</sub> = 25 °C		60	-	-	mJ



V<sub>0</sub> = 0.829 V; R<sub>s</sub> = 0.0748 Ω  
 (1) T<sub>J</sub> = -55 °C; typical values  
 (2) T<sub>J</sub> = 0 °C; typical values  
 (3) T<sub>J</sub> = 25 °C; typical values  
 (4) T<sub>J</sub> = 100 °C; typical values  
 (5) T<sub>J</sub> = 150 °C; typical values  
 (6) T<sub>J</sub> = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

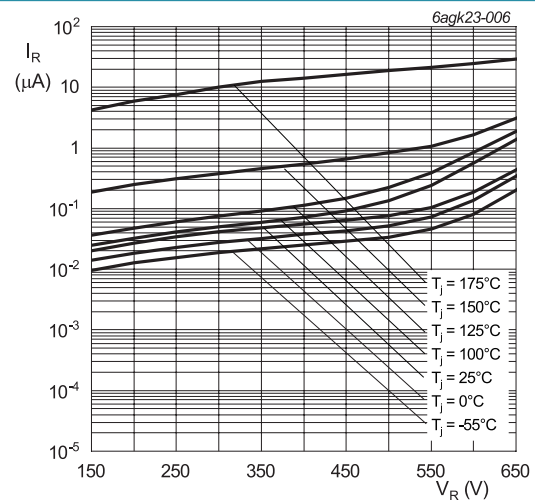
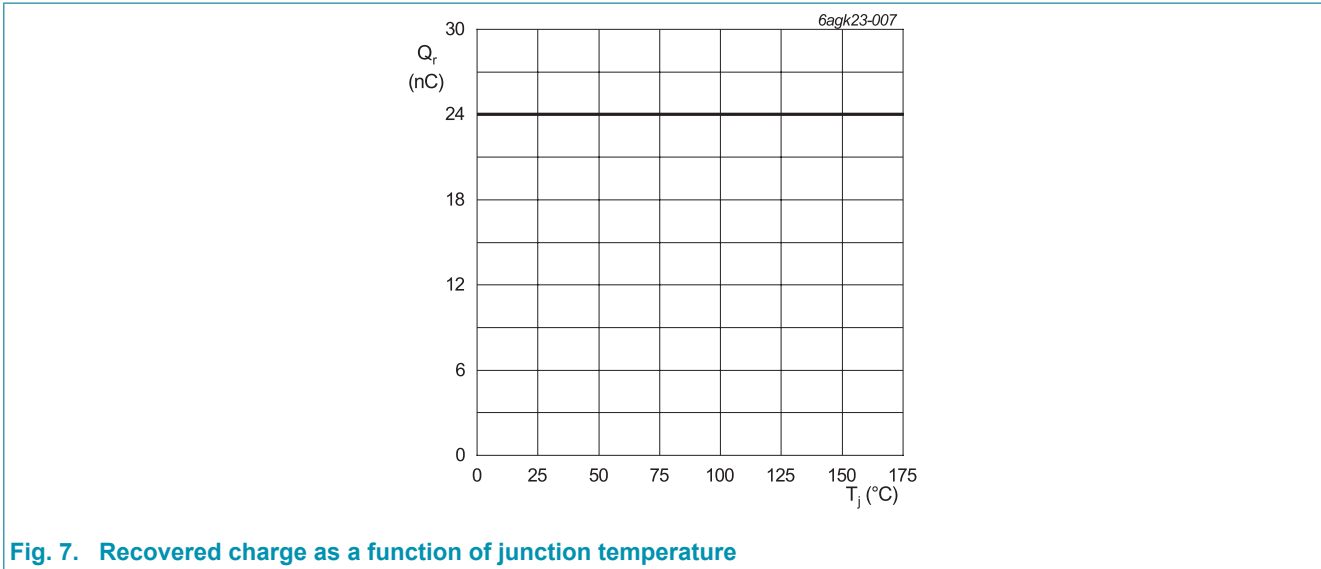
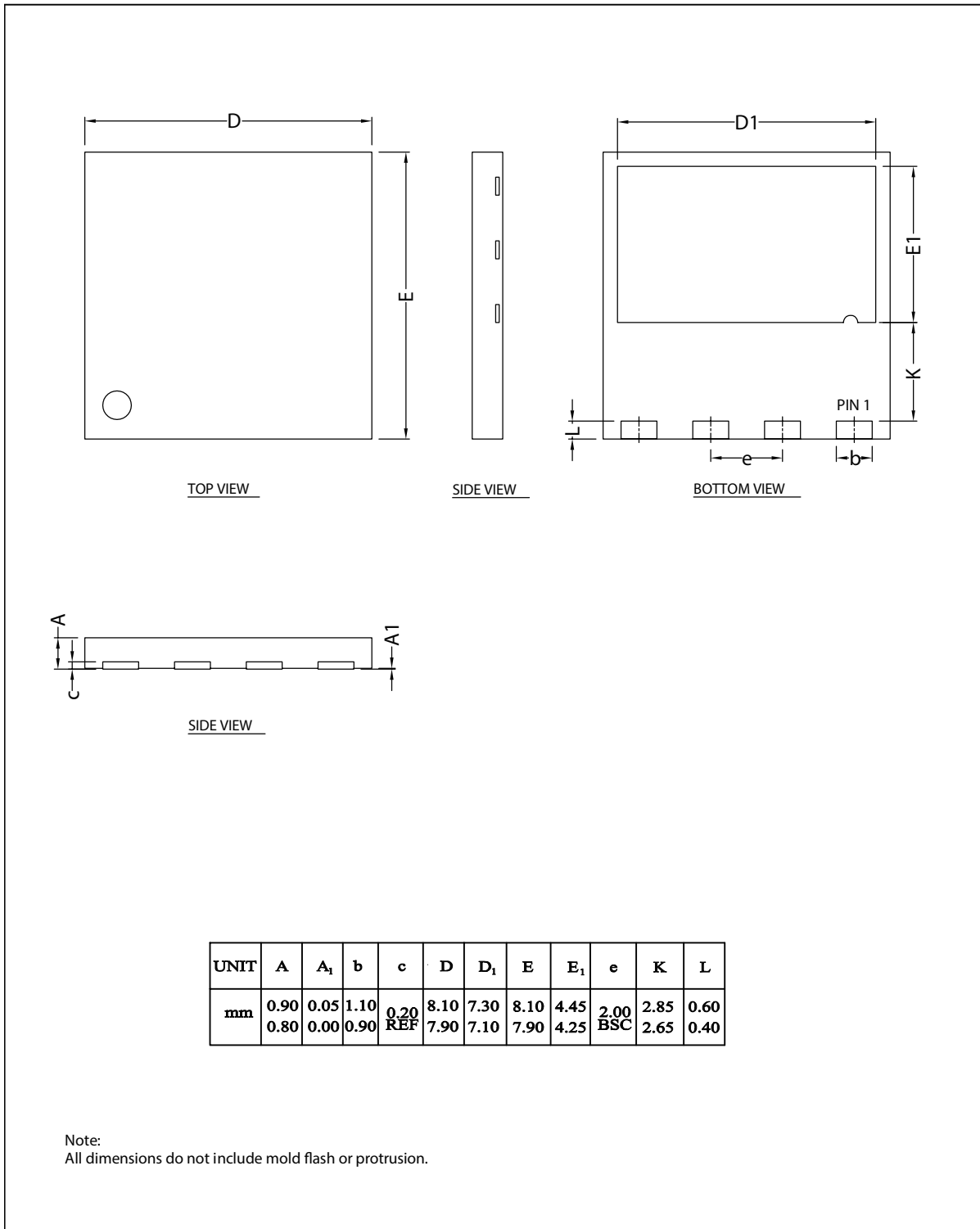


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value



### 11. Package outline





## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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### 13. Contents

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1. General description.....	1
2. Features and benefits .....	1
3. Applications .....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values .....	3
9. Thermal characteristics .....	5
10. Characteristics.....	6
11. Package outline .....	8
12. Legal information .....	9
13. Contents .....	11

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